

#### **Device Features**

- OIP3 = 32.5 dBm @ 1900 MHz
- Gain = 20.9 dB @ 1900 MHz
- Output P1 dB = 18.8 dBm @ 1900 MHz
- 50 Ω Cascadable
- Patented temperature compensation
- Patented Over Voltage Protection Circuit
- RoHS2-compliant SOT-89 SMT package

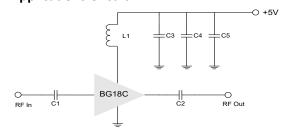


BeRex's BG18C is a high performance InGa-P/GaAs HBT MMIC amplifier is internally matched to 50 Ohms and uses a patented *temperature compensation* circuit to provide stable current over the operating temperature range without the need for external components and a patented *over voltage protection* circuit to protect a internal device. The BG18C is designed for high linearity gain block applications that require excellent gain flatness. It is packaged in a RoHS2-compliant with SOT-89 surface mount package.

#### **Applications**

- Base station Infrastructure/RFID
- · Commercial/Industrial/Military wireless system

#### **Applications Circuit**



<sup>\*</sup>C1, C2, C3 = 100 pF  $\pm$  5%; C4 = 1000 pF  $\pm$  5%; C5 = 10uF; L1 = 33nH



# Typical Performance<sup>1</sup>

Parameter		Frequency							
	500	900	1900	2140	2450	MHz			
Gain	22.4	22.2	20.9	20.6	19.9	dB			
S11	-13.1	-21.0	-26.6	-23.7	-21.1	dB			
S22	-15.5	-22.0	-28.9	-28.0	-25.7	dB			
OIP3 <sup>2</sup>	36.0	35.5	32.5	31.5	32.0	dBm			
P1dB	20.0	20.1	18.8	18.3	17.3	dBm			
Noise Figure	3.8	3.6	3.7	3.7	3.9	dB			

Device performance measured on a BeRex evaluation board at 25°C, 50 Ω system.

 $<sup>^{\</sup>rm 2}\,$  OIP3  $\_$  measured with two tones at an output of 7 dBm per tone separated by 1 MHz.

	Min.	Typical	Max.	Unit
Bandwidth	5		4000	MHz
I <sub>c</sub> @ (Vc = 5V)	63	73	83	mA
V <sub>C</sub>		5.0		V
dG/dT		-0.004		dB/°C
R <sub>TH</sub>		50		°C/W

#### **Absolute Maximum Ratings**

Parameter	Rating	Unit
Operating Case Temperature	-40 to +85	°C
Storage Temperature	-55 to +155	°C
Junction Temperature	+170	°C
Operating Voltage	+6.0	V
Supply Current	160	mA
Input RF Power	23	dBm

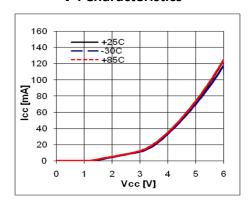
Operation of this device above any of these parameters may result in permanent damage.

<sup>\*</sup>C1,C2 = 10nF; L1 = 2.7uH for IF Bandwidth

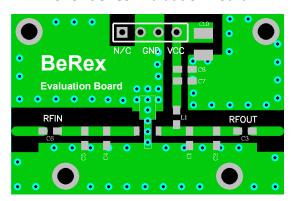
<sup>\*</sup>Optimum value of L1 may vary with board design.



#### **V-I Characteristics**



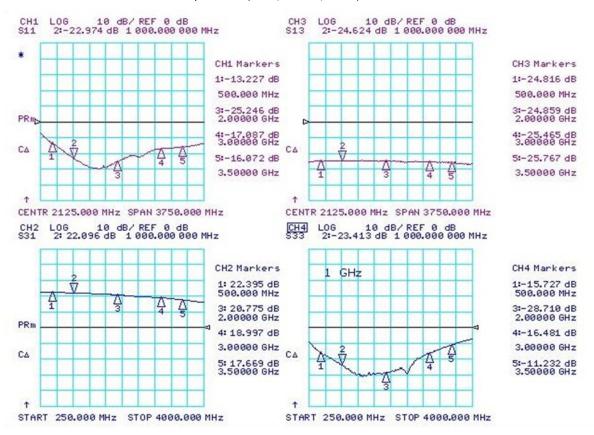
#### **BeRex SOT89 Evaluation Board**



\*Dielectric constant \_ 4.2 \*RF pattern width 52mil \*31mil thick FR4 PCB

## **Typical Device Data**

S-parameters (Vc=5V, Ic=73mA, T=25°C)



Rev. H



## **S-Parameter**

(Vdevice = 5.0V, Icc = 73mA, T = 25 °C, calibrated to device leads)

Freq	S11	S11	S21	S21	S12	S12	S22	S22
[MHz]	[Mag]	[Ang]	[Mag]	[Ang]	[Mag]	[Ang]	[Mag]	[Ang]
100	0.398	-168.6	17.517	165.4	0.046	15.8	0.372	-35.1
500	0.485	153.9	13.090	147.0	0.063	1.8	0.149	-58.8
1000	0.433	124.9	12.891	124.9	0.059	-4.6	0.075	-71.1
1500	0.365	97.1	12.062	97.6	0.064	-8.1	0.025	-35.0
2000	0.234	72.4	10.757	74.7	0.061	-17.6	0.043	41.7
2500	0.119	44.9	10.819	49.1	0.060	-22.0	0.126	38.0
3000	0.024	114.6	9.807	16.5	0.060	-26.7	0.222	24.3
3500	0.154	148.1	7.367	-11.7	0.059	-34.6	0.318	-4.0
4000	0.238	119.2	5.498	-33.1	0.058	-39.8	0.426	-30.3

Typical Performance (Vd = 5V, Ic = 73mA, T = 25°C)

Freq	MHz	70	150	250	500	900	1900	2140	2450	3500
S21	dB	23.5	23.2	22.9	22.4	22.2	20.9	20.6	19.9	19.0
S11	dB	-12.8	-14.0	-16.5	-13.1	-21.0	-26.6	-23.7	-21.1	-17.4
S22	dB	-7.9	-10.9	-13.6	-15.5	-22.0	-28.9	-28.0	-25.7	-16.5
P1	dBm	19.0	19.5	19.6	20.0	20.1	18.8	18.3	17.3	16.1
OIP3	dBm	35.0	35.5	34.5	36.0	35.5	32.5	31.5	32.0	30.0
NF	dB	3.8	3.8	3.8	3.8	3.6	3.7	3.7	3.9	3.9

Typical Performance (Vd = 4.7V, Ic = 59mA, T = 25°C)

Freq	MHz	70	500	900	1900	2140	2450	3500
S21	dB	23.5	22.5	22.1	20.5	20.2	19.4	16.6
S11	dB	-11	-17	-18	-19	-21	-31	-24
S22	dB	-7	-15	-16	-18	-20	-30	-11
P1	dBm	18.2	18.3	18	17.6	17.8	15.8	
OIP3	dBm	33.5	33.5	32.5	31	31	29.5	
NF	dB	3.8	3.8	3.6	3.7	3.7	3.9	

Rev. H



### Typical Performance (Vd = 4.5V, Ic = 52mA, T = 25°C)

	•			•				
Freq	MHz	70	500	900	1900	2140	2450	3500
S21	dB	23.1	22.2	21.9	20.7	20.5	19.8	16.5
S11	dB	-11	-16	-17	-19	-20	-30	-24
S22	dB	-7	-14	-16	-18	-20	-29	-11
P1	dBm	17.3	17.2	16.7	16.8	17.2	15.4	
OIP3	dBm	32	32	31	30	29.5	29	
NF	dB	3.8	3.8	3.6	3.7	3.7	3.9	

### Typical Performance (Vd = 4.0V, Ic = 35mA, T = 25°C)

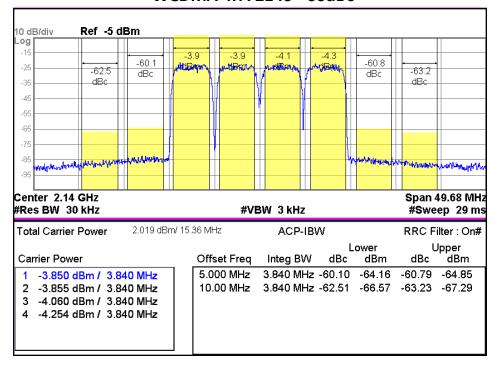
Freq	MHz	70	500	900	1900	2140	2450	3500
S21	dB	22.6	21.8	21.4	20	19.8	19.1	16.2
S11	dB	-10	-14	-14	-17	-18	-24	-26
S22	dB	-8	-13	-13.6	-16	-18	-25	-11
P1	dBm	13.9	13.6	12.9	13.5	15.3	14	
OIP3	dBm	26	25	25	25	26	26	
NF	dB	3.7	3.7	3.5	3.7	3.7	3.8	

## Typical Performance (Vd = 3.5V, Ic = 21mA, T = 25°C)

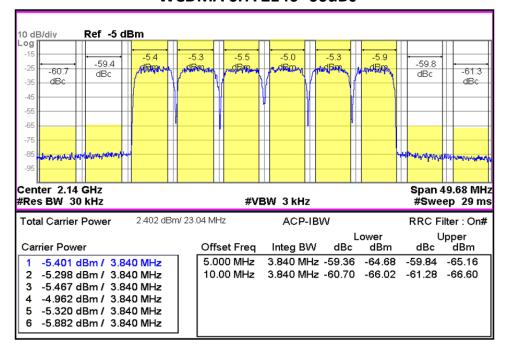
Freq	MHz	70	500	900	1900	2140	2450	3500
S21	dB	20.4	20	19.6	18.7	18.8	18.4	15.7
S11	dB	-7	-9	-9.6	-11	-12	-15	-27
S22	dB	-5	-9	-9.6	-11	-13	-17	-13
P1	dBm	8.1	7.1	6.4	7.1	10.4	12.5	
OIP3	dBm	19.5	18.5	17	16	17	17.5	
NF	dB	3.6	3.6	3.5	3.6	3.7	3.8	



#### WCDMA 4FA 2140 -60dBc

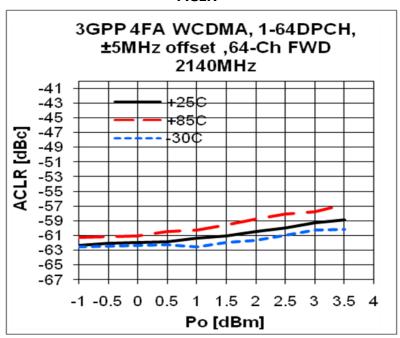


#### WCDMA 6FA 2140 -60dBc



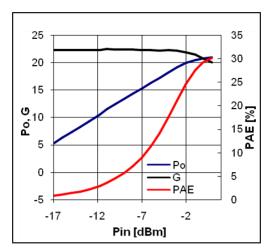


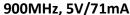
### **ACLR**

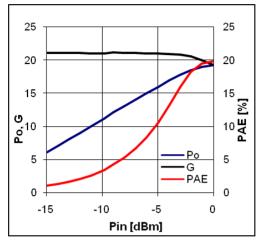


### **Device Performance**

#### Pin-Pout-Gain





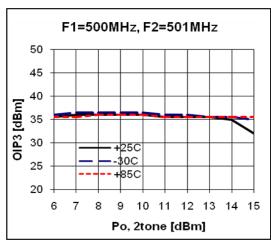


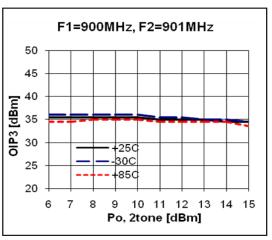
1900 MHz, 5V/71mA

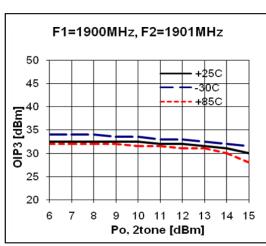


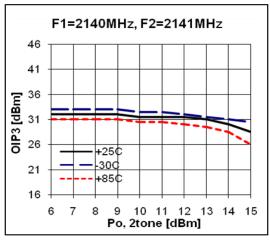


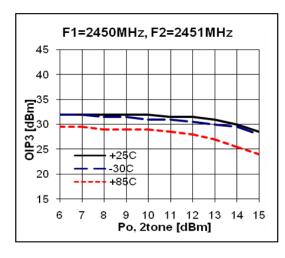
### OIP3

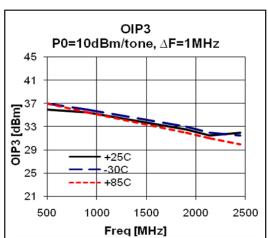






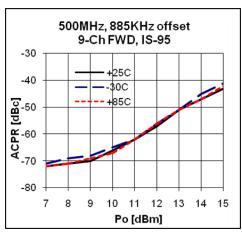


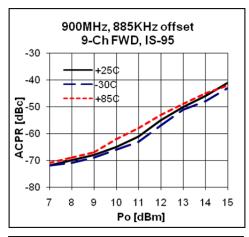


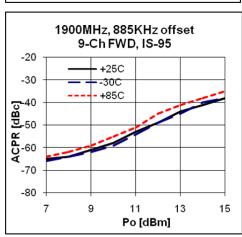


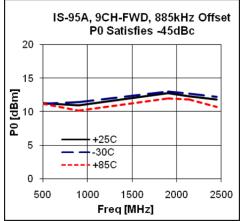


## **ACPR**

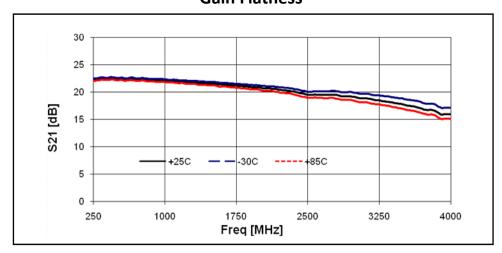






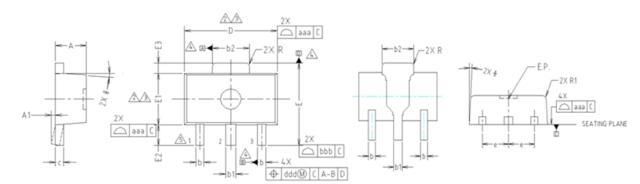


## **Gain Flatness**





# **Package Outline Dimension**



NOTE:

1. DIMENSIONS IN MILLIMETERS.

DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 8.5mm PER END.

DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.

INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 8.5mm PER SIDE.

DIMENSIONS D AND E1 ARE DETERMINED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

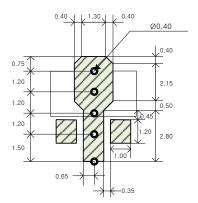
A DATUMS A, B AND D TO BE DETERMINED 8.18mm FROM THE LEAD TIP.

TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

		MILLI	METERS		NOTE
SYMBOL	MINIMUM	NON	JINAL	MAXIMUM	NOIE
A	1.40	1	.50	1.60	
A1	0.00	0.00		0.10	
Ь	0.38	(	).42	0.48	
Ь1	0.48	0	).52	0.58	
b2	1.79	1	.82	1.87	
C	0.40	0	.42	0.46	
D	4.40	4	.50	4.70	2,3
Ε	3.70	4	.00	4.30	
E E1	2.40	2	.50	2.70	2,3
E2	0.80	1	.00	1.20	
E3	0.40	0	.50	0.60	
e		1.5	0 TYP.		
0			TYP.		
R		0.1	5 TYP.		
R1	-		_	0.20	
SYMBOL	TOLERANCES OF AND POSI	FORM TION	NOTE		
aaa	0.15				
bbb	0.20				
ccc	0.10				
ddd	0.10				

# **Suggested PCB Land Pattern and PAD Layout**

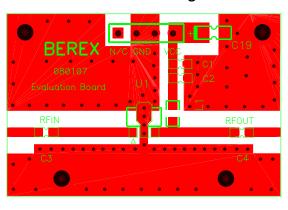
#### **PCB Land Pattern**



Note: All dimension \_ millimeters

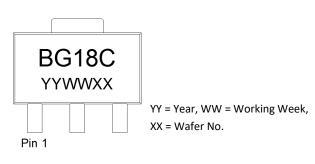
PCB lay out \_ on BeRex website

#### **PCB Mounting**



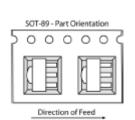


# **Package Marking**



# Tape & Reel

**SOT89** 



Packaging information:

Tape Width (mm): 12
Reel Size (inches): 7
Device Cavity Pitch (mm): 8

Devices Per Reel: 1000

# Lead plating finish

100% Tin Matte finish

(All BeRex products undergoes a 1 hour, 150 degree C, Anneal bake to eliminate thin whisker growth concerns.)

# MSL / ESD Rating

**ESD Rating:** Class 1C

Value: Passes <2000V

Test: Human Body Model (HBM)

**Standard:** JEDEC Standard JESD22-A114B

MSL Rating: Level 1 at +265°C convection reflow

Standard: JEDEC Standard J-STD-020



Proper ESD procedures should be followed when handling this device.

### **NATO CAGE code:**

2 N 9 6 F
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**BeRex** 

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●email: <u>sales@berex.com</u>

Rev. H